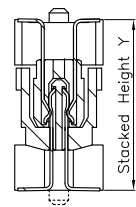
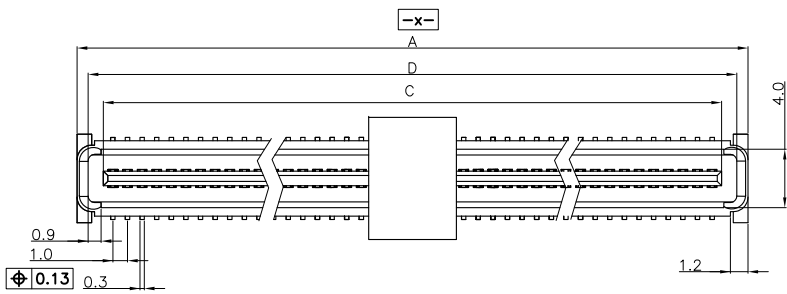


REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN190121	



Material and plating:

Housing: LCP, UL94V-0, BLACK.

Contact: Phosphor copper

Gold Plated on Contact Area and 80u" Min Tin or Gold Flash Plated on solder tail over Nickel 50u" Min

Electrical Characteristics:

Current Rating: 0.5 AMP.

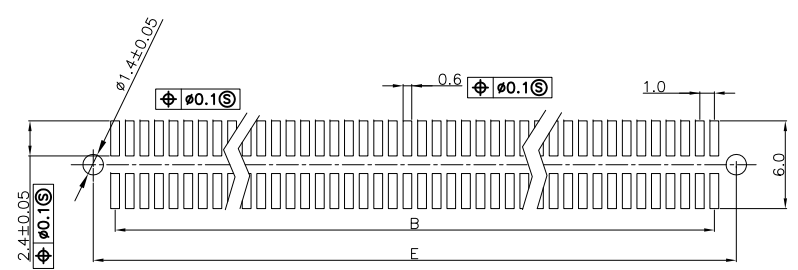
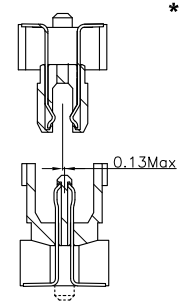
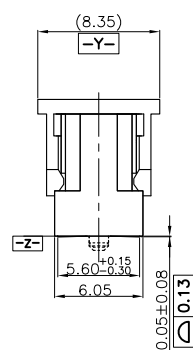
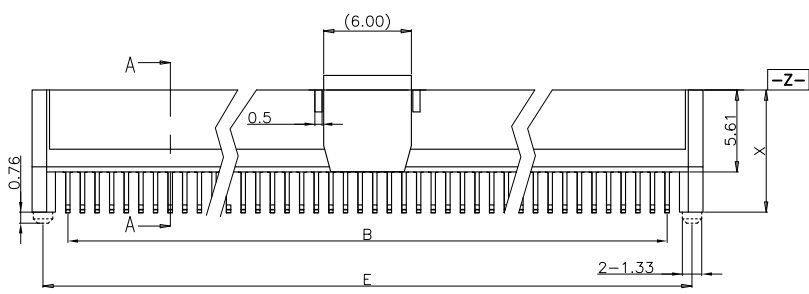
Dielectric Withstanding Voltage: AC 500V For 1 minute.

Insulator Resistance: 100MΩ min. at DC 100V.

Contact Resistance: 40mΩ max. at DC 1mA.

Operating Temperature: -40°C~+85°C .

***RoHS Compliant**



P.C.Board Layout

Series 2349- xx G xx D x N x T - x

Position
 G: Gold Plated
 C: Selective Gold Plated
 00: G/F
 10: 10μ"
 15: 15μ"
 30: 30μ"
 D: SMD Type
 P: With Post
 N: Without Post

P: Plastic Pad (Black)
 S: Mylar
 T: Tape & Reel Package
 Code 1
 Code 2
 Code 3
 Blank: Black
 N: Beige

Code		Pos.	Dimension										
H1	H2		A	B	C	D	E						
		14	10.90	6.00	7.30	9.38	9.40						
		18	12.90	8.00	9.30	11.38	11.40						
*	*	20	13.90	9.00	10.30	12.38	12.40						
*	*	30	18.90	14.00	15.30	17.38	17.40						
*	*	34	20.90	16.00	17.30	19.38	19.40						
		36	21.90	17.00	18.30	20.38	20.40						
*	*	40	23.90	19.00	20.30	22.38	22.40						
		50	28.90	24.00	25.30	27.38	27.40						
*	*	64	35.90	31.00	32.30	34.38	34.40						
*	*	80	43.90	39.00	40.30	42.38	42.40						
*	*	84	45.90	41.00	42.30	44.38	44.40						
		100	53.90	49.00	50.30	52.38	52.40						
code:1~4 X		1	1	1	2	2	2	3	3	3	4	4	4
2348		5.37	5.37	5.37	7.37	7.37	7.37	8.37	8.37	8.37	10.37	10.37	10.37
code:1~3 X		1	2	3	1	2	3	1	2	3	1	2	3
2349		6.35	7.35	8.35	6.35	7.35	8.35	6.35	7.35	8.35	6.35	7.35	8.35
stacked height Y		8.0	9.0	10.0	10.0	11.0	12.0	11.0	12.0	13.0	13.0	14.0	15.0

Tolerances	Dwg No.	2349-D0000-002	
x = ±0.5	Projection		
.x = ±0.25	Unit	mm	Scale 1:1
.xx = ±0.15	Drawn By	QHX	01/22'19

Title: 2349 Series
 Board to Board 1.0mm
 Male Type

OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 2349-xxG(C)xxDxNxT-x			
SHEET	1/1	Ver. No.	R3